



SUSS MICROTEC INVESTOR PRESENTATION

March 2013

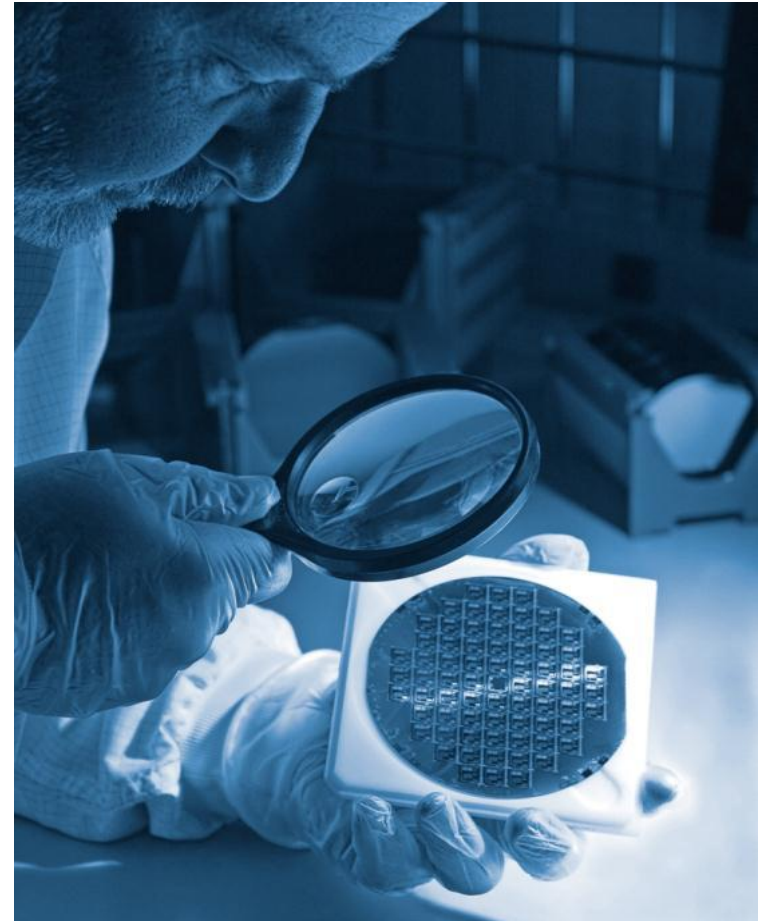
This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

- I. SUSS MicroTec at a Glance**
- II. Products and Markets
- III. Growth Opportunities
- IV. Enhancement of Lithography Portfolio
- V. Financials
- VI. Outlook

- + SUSS MicroTec: A global leader in semiconductor equipment
- + Our equipment and process solutions create the micro structures that build and connect micro electronic devices
- + We are focused on high growth market segments: Semiconductors, MEMS, LEDs

+ Key Data:

- Stock Exchange Symbol: SMHN
- TecDAX
- Share price*: 9.12 €
- Market Cap*: 174 € million
- Net Cash, December 2012: 32.3 € million



* January 31, 2013

EXTENSIVE PRODUCT PORTFOLIO



Photomask Equipment



Coater/Developer



Wafer Bonders



**Alignment
Verification Systems**



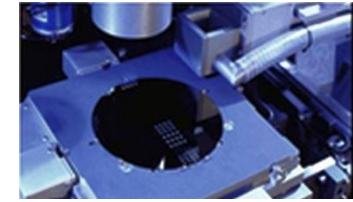
Mask Aligners



Imprinting Systems

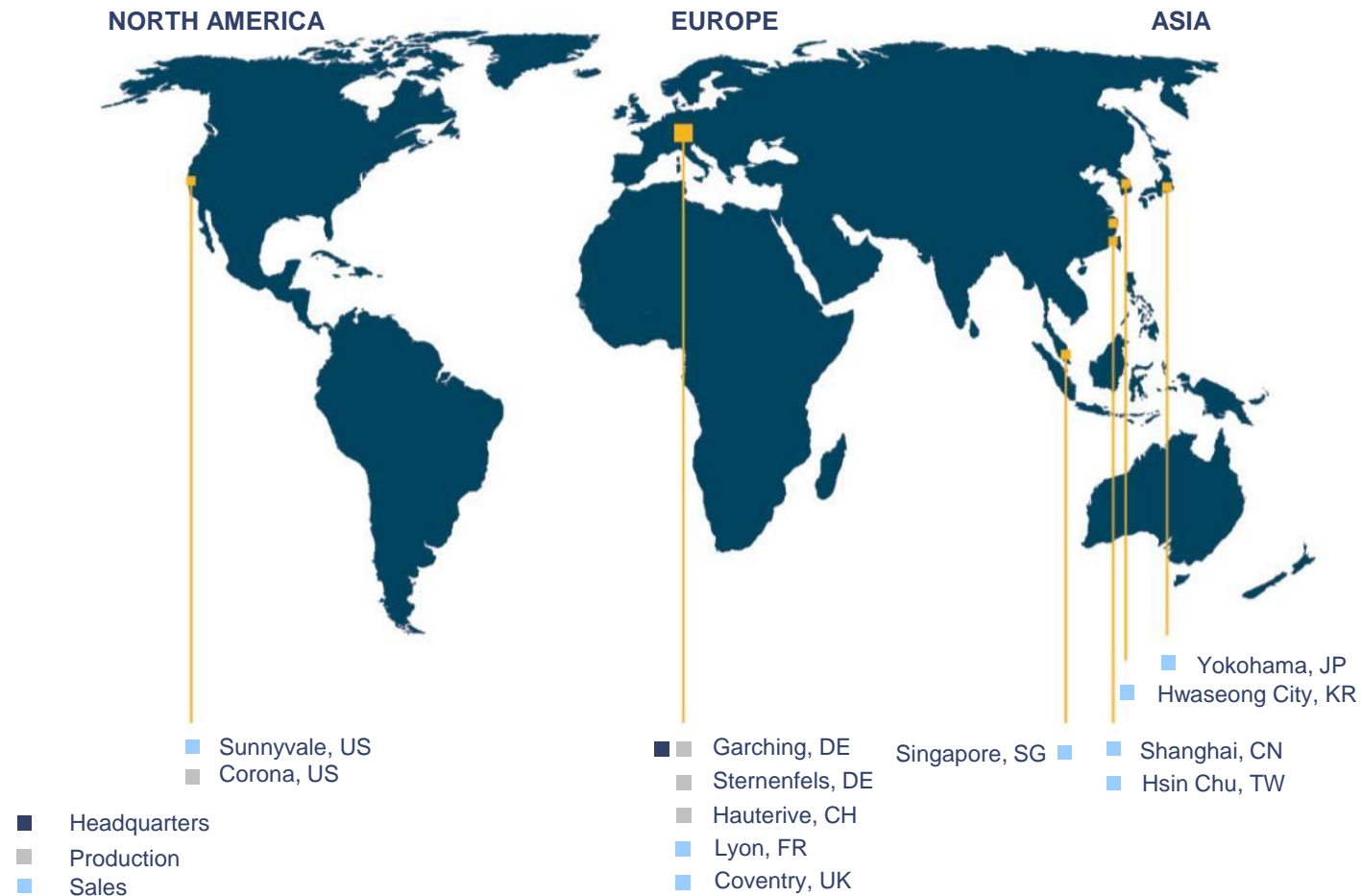


**UV-Projection
Stepper / Scanner**



**Excimer Laser
Systems**

SUSS MICROTEC – A GLOBAL PLAYER



Germany



Garching

- + SUSS MicroTec HQ
- + Development/production:
 - **Mask Aligner**
 - **Bond Aligner**
- + Core competencies:
 - **Exposure**
(proximity exposure)
 - **Alignment**



Sternenfels

- + Development/production :
 - **Bonder**
 - **Coater and Developer**
 - **Photomask Equipment**
- + Core competencies:
 - **Wet processing**
 - **Wafer bonding**

USA

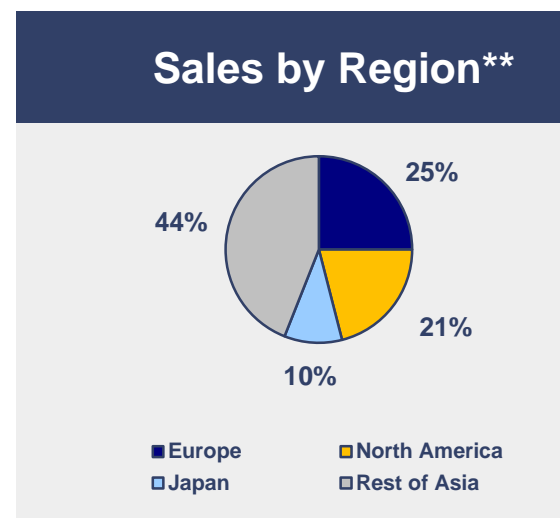
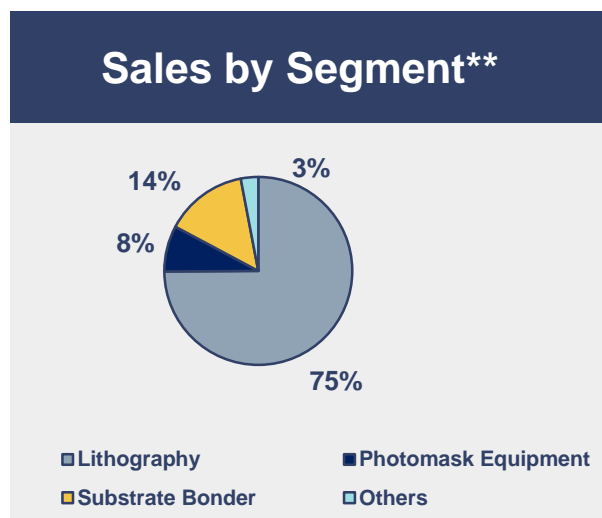


Corona

- + Development/production:
 - **Stepper/Scanner**
 - **Laser Processing**
- + Core competencies:
 - **Exposure**
(UV projection lithography)
 - **Laser Ablation**

KEY NUMBERS*

in € million	2012	2011	YoY in %
Revenue	163.8	175.4	-6.6%
Order Intake	157.2	143.1	9.9%
Order Backlog 12/31	86.5	83.7	3.3%
EBIT	11.7	18.6	-37.1%



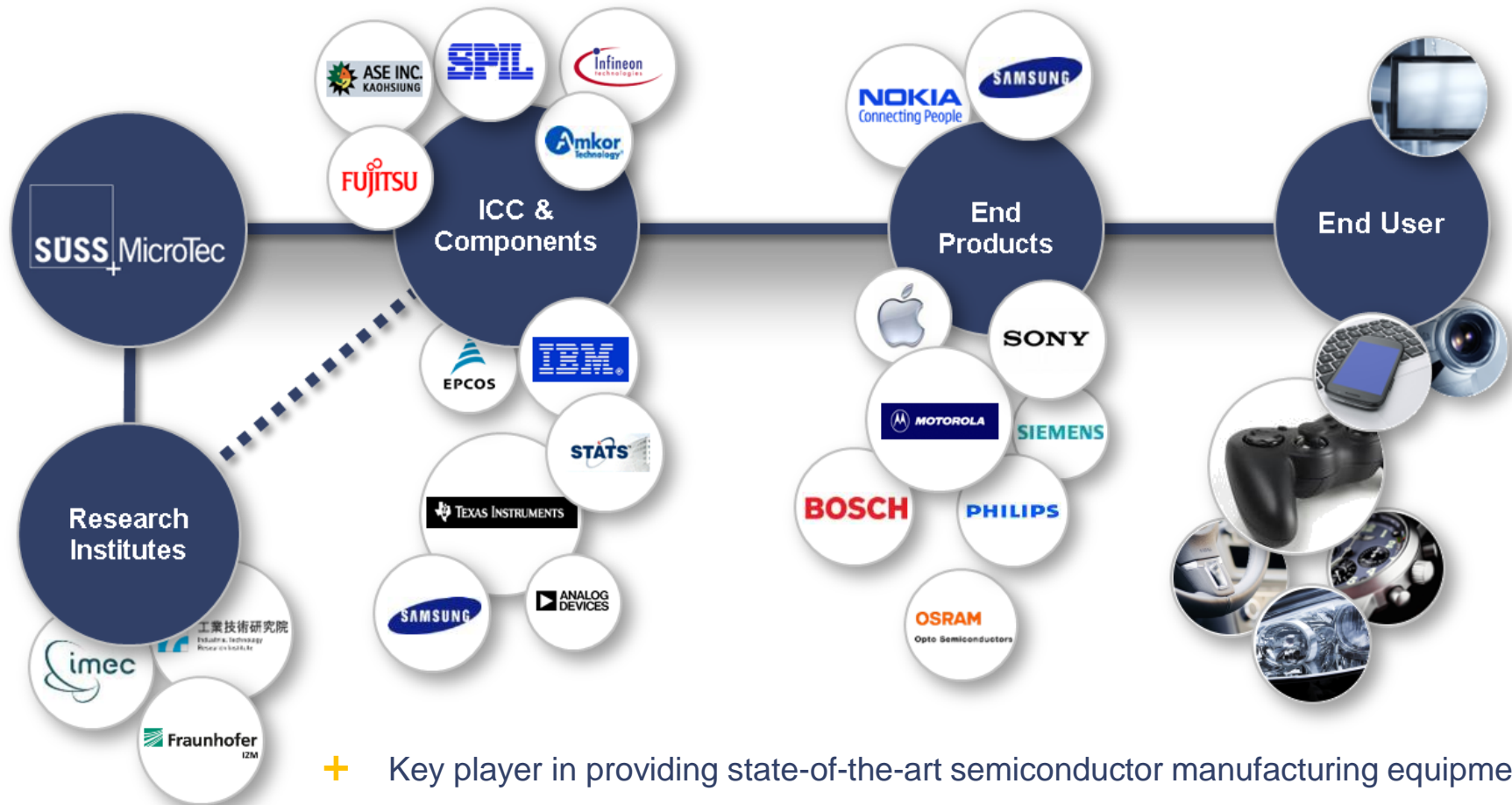
*Based on preliminary numbers

** Based on 9m figures

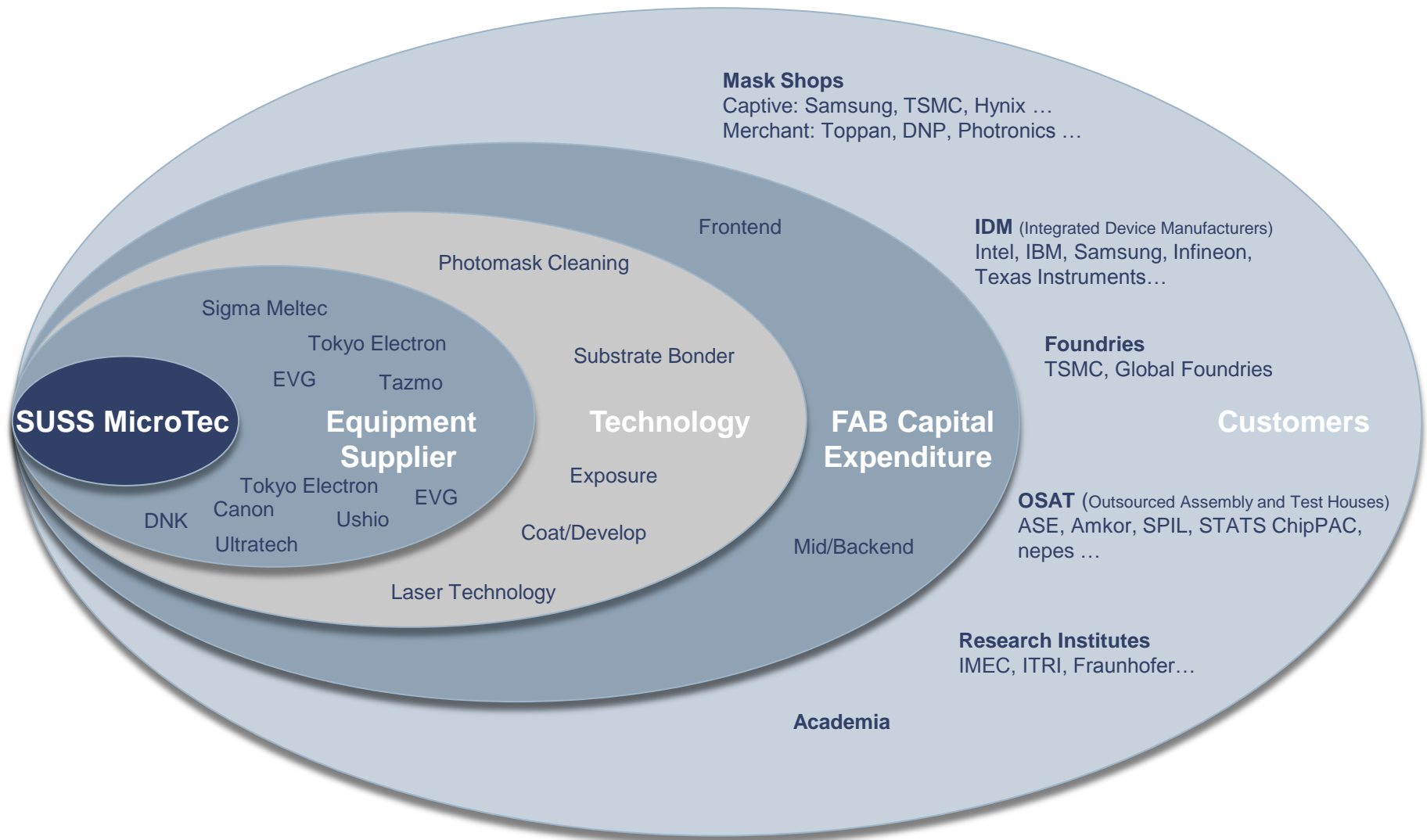
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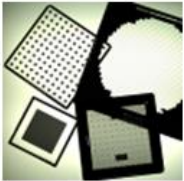
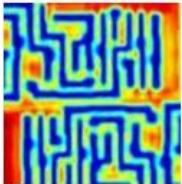
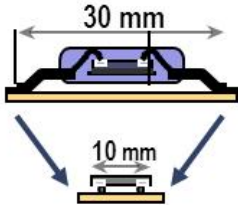
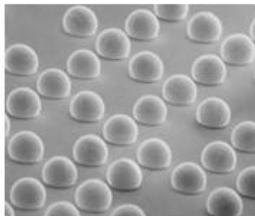
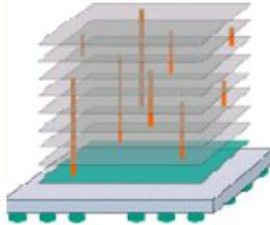
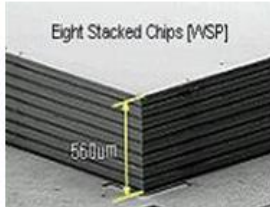

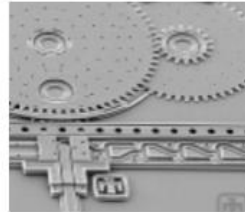
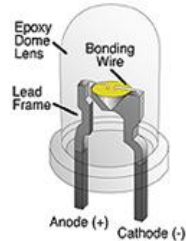

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SUSS MICROTEC IN THE VALUE CHAIN

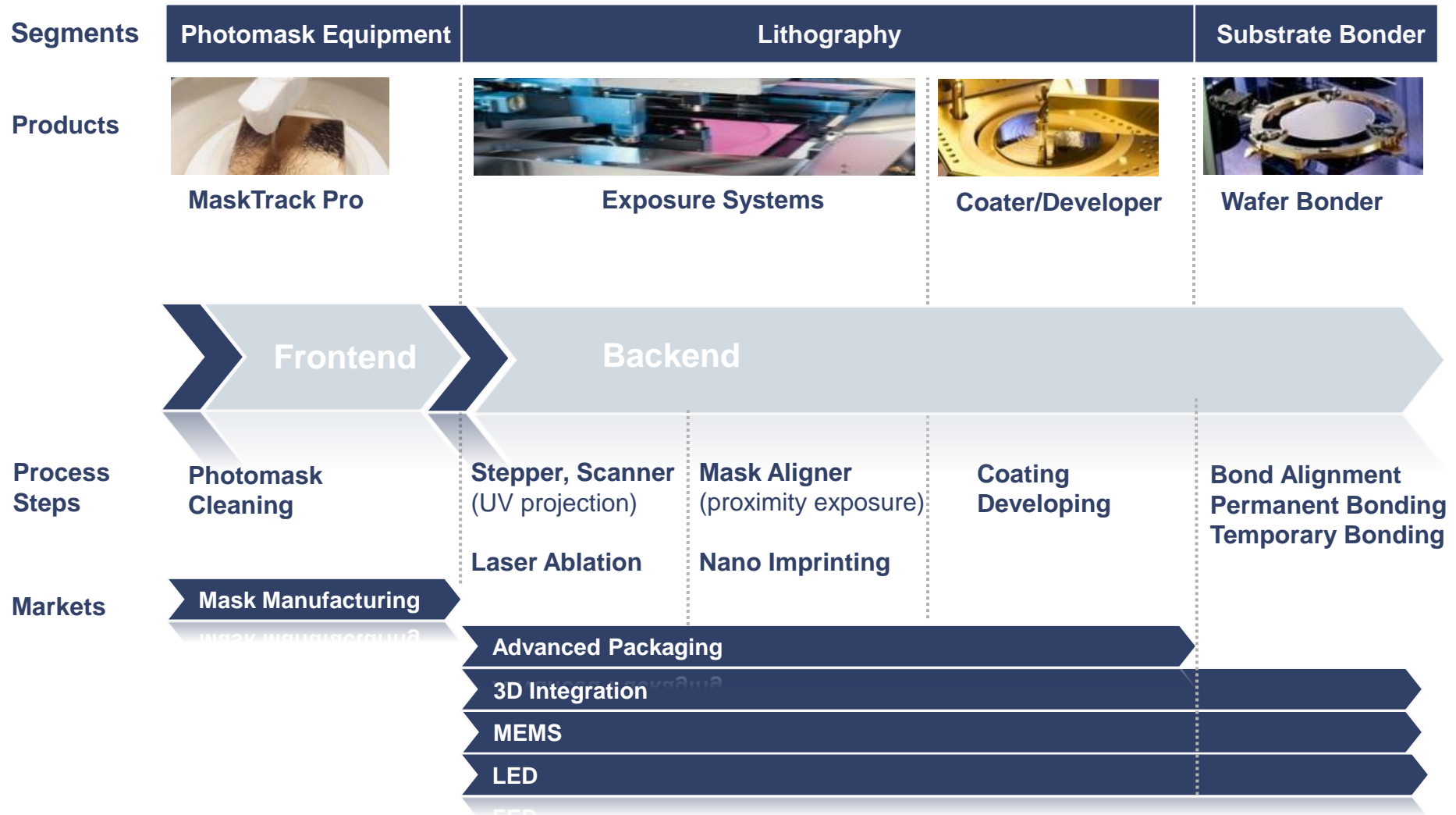


- + Key player in providing state-of-the-art semiconductor manufacturing equipment
- + Development of highly innovative process solutions with industry and R&D partners
- + Components for electronic devices like cell phones, PCs and tablet computers are produced on SUSS MicroTec's equipment



Semiconductors			Sensors	Lighting
Mask Manufacturing Photomask Cleaning	Advanced Packaging Micro-Bumping	3D Integration/Stacking	MEMS Computing, Automotive, Medical Applications ...	LED General Lighting, HB and UHB LED
 	 	 	 	 

SEGMENTS AND MARKETS



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MICROCHIPS, MEMS UND LED: BUILDING BLOCKS FOR TECHNOLOGICAL PRODUCT ADVANCEMENT

Digital Lifestyle

- The „Digital Lifestyle“ is characterized by permanent internet connectivity and convergence of media
- Mobile devices like smartphones and tablet PCs provide this capability at affordable cost
- New device generations offer higher functionality



E-Mobility

- Alternative transportation / mobility solutions are getting more traction with attractive price / performance ratios
- Evs, Hybrid-Cars, Segways, E-Bikes, but also trains drive the need for power devices but also high performance ICs



Energy Efficiency

- Increase environmental awareness and rising energy prices and fuel the demand for energy efficient solutions in electricity usage i.e. lighting
- Energy efficiency in industrial production
- Smart energy management in household applications saves energy



EXPECTED MARKET DEVELOPMENTS

With its strong position in the fast growing target markets 3D Integration / Advanced Packaging, LED and MEMS, SUSS MicroTec can benefit from the market developments:

Advanced Packaging

Wafer level packaging and flip chip is expected to remain more robust than the overall market, primarily driven by mobile devices like smart phones and tablets

3D Trough Silicon Vias (TSV)

Transition to production volume in the years to come

Compound Semiconductors

LED, MEMS, RF, Optoelectronics, III-V Power are expected to remain robust based on smartphone and tablet growth and will drive further demand for advanced packaging solutions

Segment growth 2011 - 2016E CAGR ~ 15% (Gartner and industry estimates)

SCALING TECHNOLOGIES FROM 2D TO 3D

2D Packaging

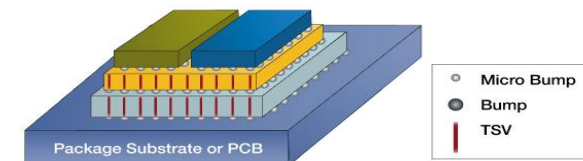
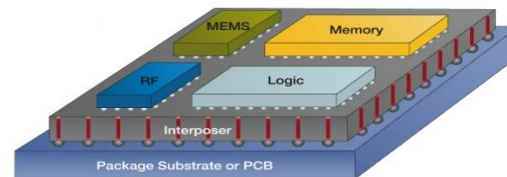
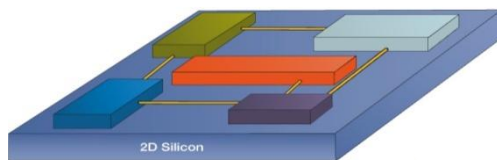
- Increased performance and complexity of ICs by shrinking transistor geometry according to Moore's Law
- New technologies like EUV and multiple patterning allow further scaling
- Technical challenges and limitations make it increasingly more difficult and expensive to reduce the feature size

2.5D Packaging

- Combining of several (and heterogeneous) semiconductor components on an interposer addresses limitations of traditional shrinking
- Increased packaging density
- Reduced footprint
- Complementary technology to Moore's Law

3D Integration

- The extension beyond the conventional shrink roadmap is called "More than Moore"
- Packaging becomes key enabler for scaling and some manufacturing value is shifting from silicon to the package
- Performance and complexity increase combined with smaller footprint
- Reduced energy consumption



SUSS MicroTec's equipment and process solutions enable 2D shrinking ("*Moore's Law*") and 3D stacking ("*More than Moore*")

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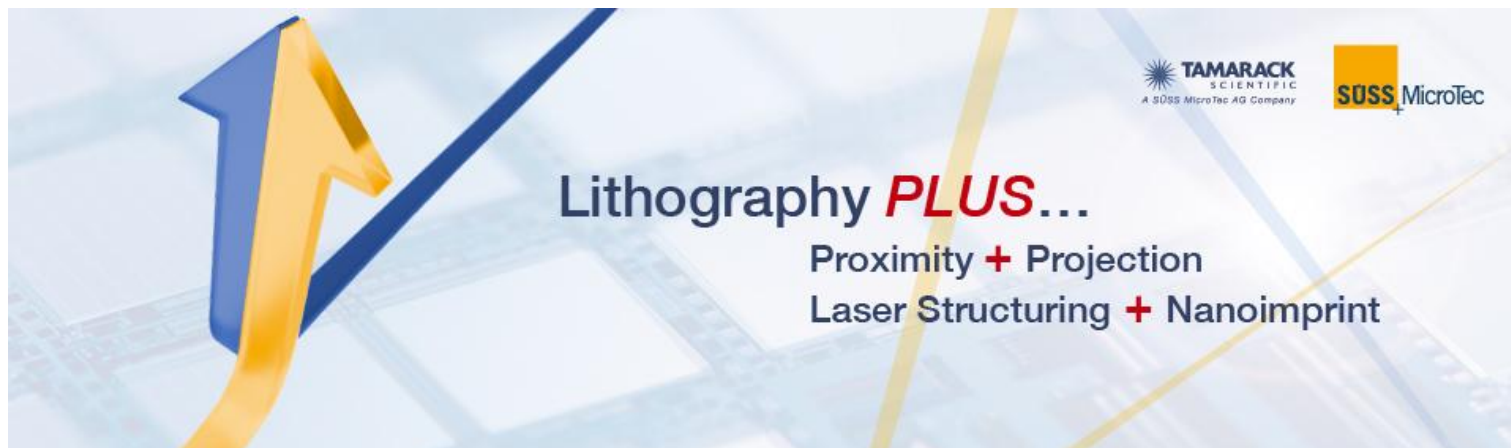
- + Tamarack Scientific develops and builds UV projection lithography systems and laser micro-structuring tools
- + Tamarack targets the same high growth market segments as SUSS MicroTec: Advanced Packaging, 3D Integration, MEMS and LED

+ Key Data:

- Founded 1966, based in Corona, California
- Installed base larger than 1,100 systems
- Revenues FY11/12: app. 10 million €
- 63 employees
- Total purchase price 9.34 million \$
(plus additional variable earn-out component)



- + Increasing chip performance requires adoption of innovative lithography technologies in the semiconductor backend
- + **Not one technology fits all needs**
- + Add new and highly complementary product line with the core technologies UV projection lithography and laser micro-structuring
- + SUSS MicroTec's global sales and support structure plus Tamarack's technology offering enable the expansion of SUSS MicroTec's lithography footprint
- + SUSS MicroTec as a financially strong and globally positioned company can unlock the potential of Tamarack and enable high future growth



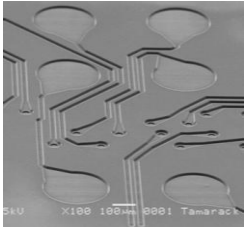
Our Lithography Solutions

EVOLUTION REVOLUTION

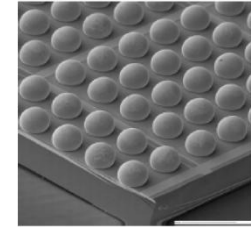
- + Established:**
 - Proximity Exposure Systems
 - NanoImprint
- + Evolution:**
 - Innovative UV Lithography Alternatives:
 - Full field projection scanner
 - Projection stepper
- + Revolution:**
 - Laser Patterning



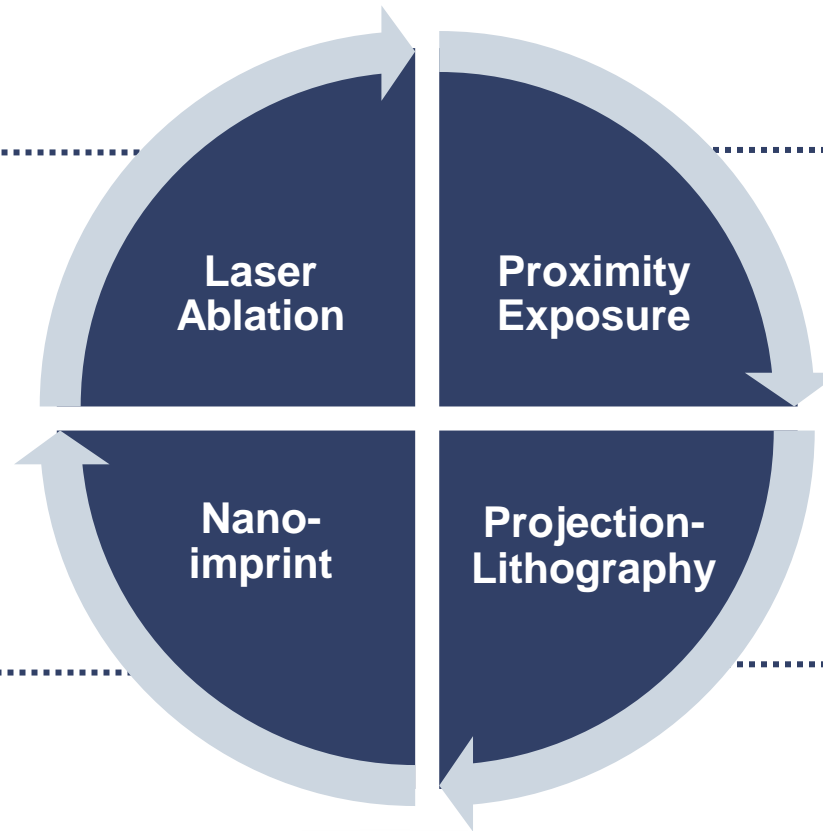
**SUSS MicroTec to become the leading provider
for mid- and backend lithography systems**



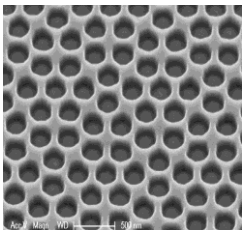
WLCSP:
Fanout WLP



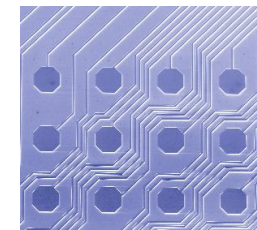
Flip Chip:
Solder Bumping



LED:
Photonic Crystals



WLCSP:
Fine pitch RDL



- Micro-optical arrays are important optical elements to enhance the performance of lithography solutions
 - For SUSS MicroTec this is a key competence
- SUSS MicroOptics is leading supplier for advanced micro-optics
 - Field of use is mainly semiconductor lithography (i.e. Carl Zeiss, SUSS MicroTec), telecommunications and R&D
- Our innovation and technology leadership position is a solid base for continuous future growth
 - Over the last 10 years a CAGR of 20% could be achieved

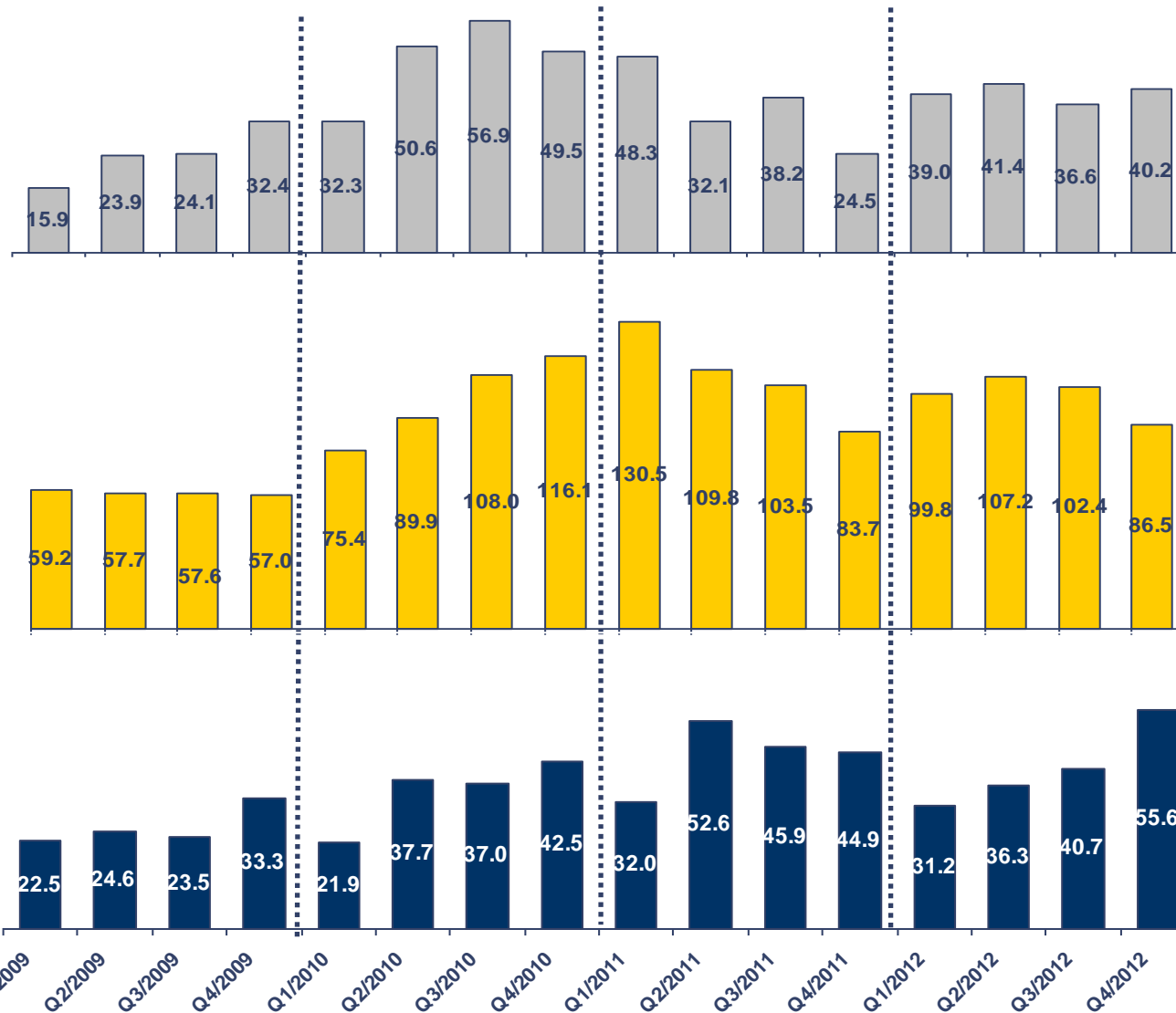
A new production facility increases capacity to meet market demand:

- Class 100/1000 cleanroom (415sqm)
- Total investment of more than € 2 million
- Production start mid December 2013
- New fab allows to move from one shift (8h/5d) to 24/7 operation



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LONG TERM BUSINESS DEVELOPMENT



Order Entry

in € million

2012: € 157.2 million

Order Backlog

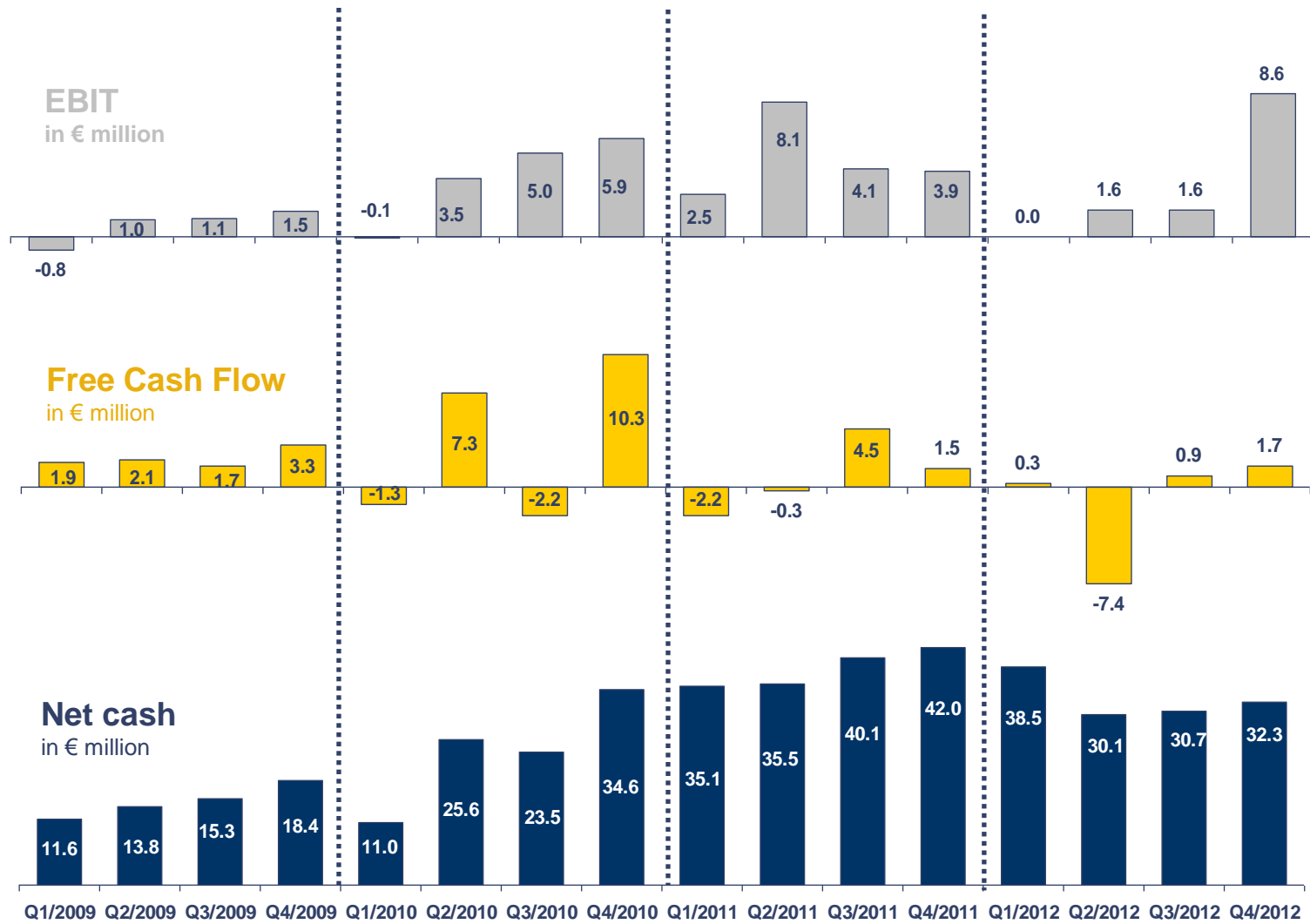
in € million

Sales

in € million

2012: € 163.8 million

EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



KEY FINANCIALS (PRELIMINARY NUMBERS)

in € million	2012	2011	YoY in %
Revenue	163.8	175.4	-6.6%
Order Intake	157.2	143.1	9.9%
Order Backlog 12/31	86.5	83.7	3.3%
EBIT	11.7	18.6	-37.1%
<i>EBIT in % of Sales</i>	<i>7.1%</i>	<i>10.6%</i>	<i>-3.5%pt.</i>
Net Cash*	32.3	42.0	-23.1%
Free Cash Flow**	-4.5	3.5	<-100%

*incl. stock of interest-bearing securities

**before consideration of purchased interest-bearing securities and M&A activities

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Guidance

- + FY 2013:
 - Sales of approximately 150 € million
 - EBIT: low single digit € million amount

Investment Case

- + Strong fundamental growth in target markets
- + Strong competitive positioning:
first or second in the target markets
- + Leading equipment company in the semiconductor backend, enabling “Moore’s Law” as well as “More than Moore”
- + Significant mid term revenue opportunity
- + Play active role in the consolidation of the backend



Thank you!

SÜSS MicroTec AG
Schleissheimer Str. 90
85748 Garching

www.SUSS.com

Contact

Franka Schielke

Tel.: +49 (0) 89-32007- 161

Fax.: +49 (0) 89-32007- 451

Email: franka.schielke@suss.com

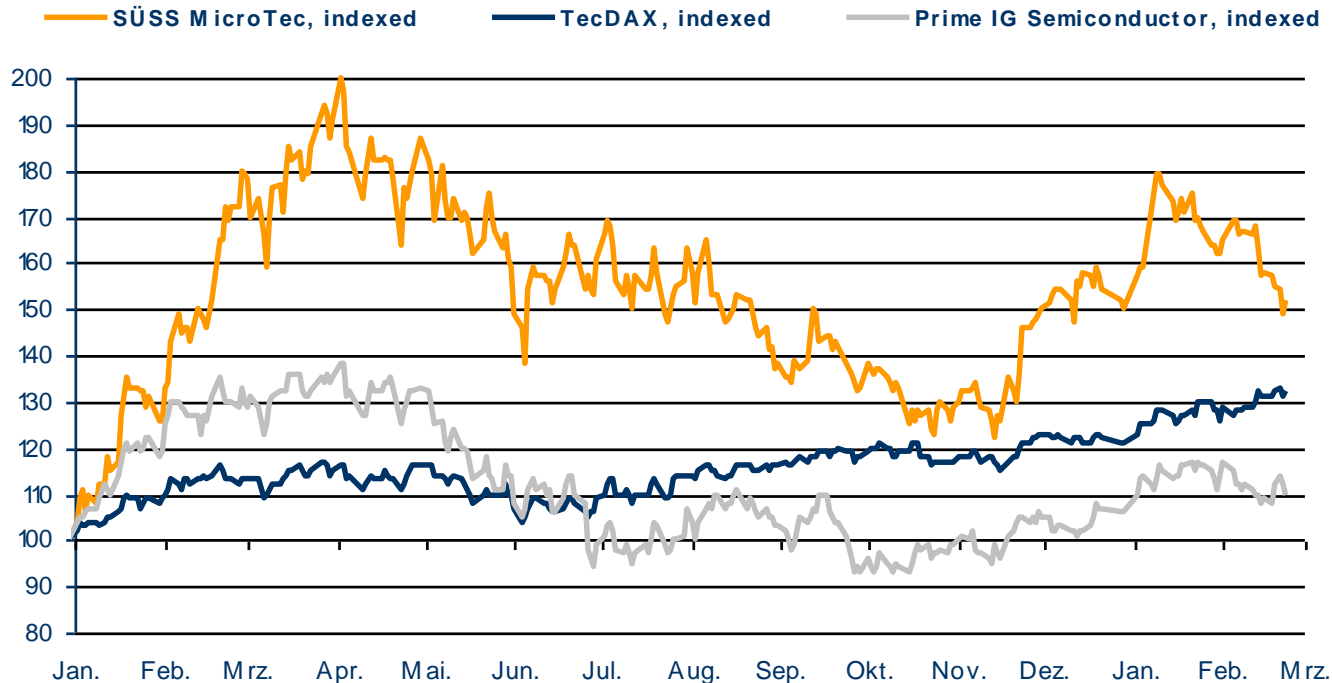
SÜSS MicroTec AG
Schleissheimer Strasse 90
85748 Garching (Munich)
Germany
www.suss.com

Financial Calendar 2013

Cheuvreux German Corporate Conference, Frankfurt/Main	21. Jan.
Annual Report 2012	28. Mar
Quarterly Report 2013	8. May
Commerzbank German Midcap Conference, Boston/New York	22./23. May
Shareholders' Meeting, Haus der Bayerischen Wirtschaft, Munich	19. Jun.
Interim Report 2013	8. Aug.
Commerzbank TMT Conference, Frankfurt	28. Aug
UBS Best of Germany Conference, New York	16. - 18. Sep
UniCredit/Kepler Investment Conference, Munich	24. - 26. Sep
Baader Investment Conference, Munich	24. - 26. Sep
Nine-month Report 2013	7. Nov.
German Equity Forum, Frankfurt/Main	11. - 13. Nov

SUSS MICROTEC SHARE PRICE DEVELOPMENT

(Price of the SUSS MicroTec Share at December 30, 2011, € 5.63)



Major Shareholders:

DWS Germany 8.68%

Credit Suisse Switzerland 3.35%

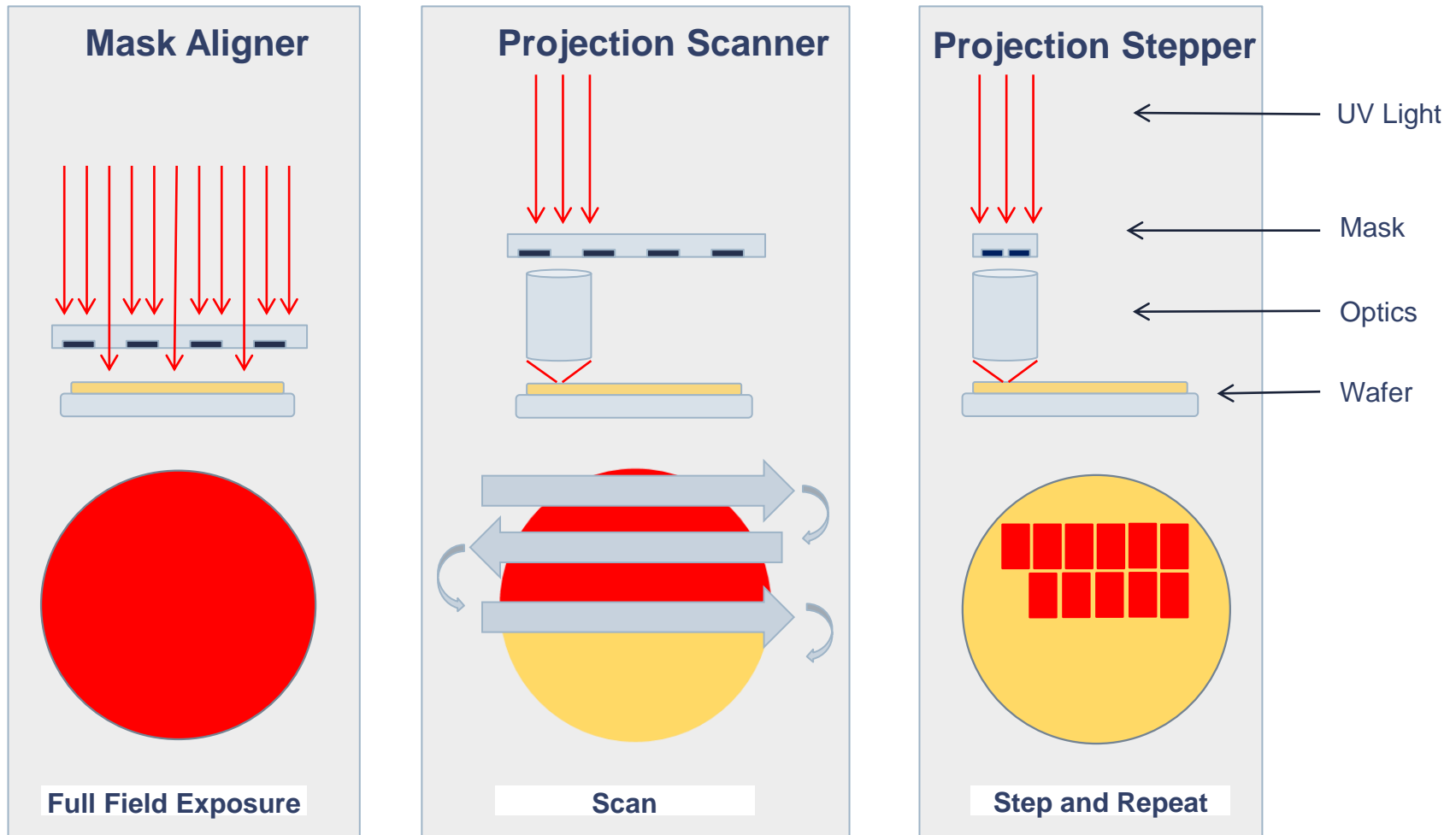
BlackRock 3,23%

Henderson Global Invest. 3.14%

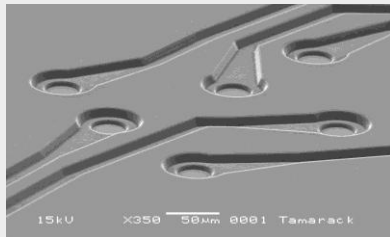
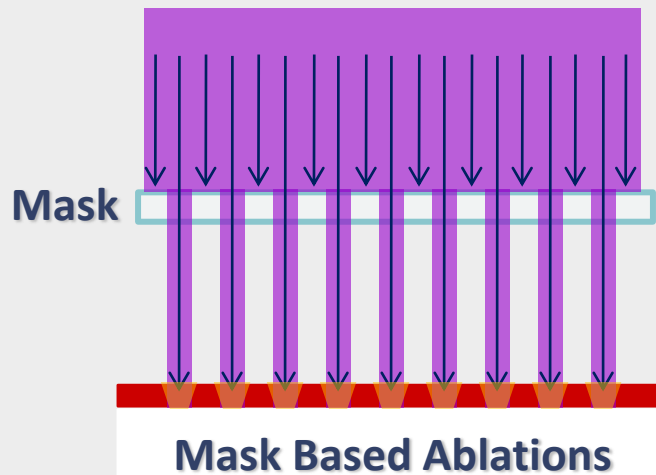
DWS Luxembourg 3.04%

Average daily trading volume 2012/13: ~ 118,000

OVERVIEW SUSS MICROTEC LITHOGRAPHY TECHNOLOGIES – EXPOSURE

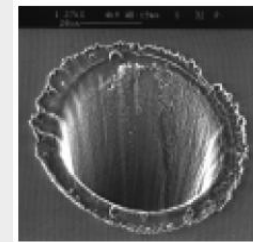


Excimer Laser Large-area Ablations



*Ablation of complex structures
(i.e. RDL trench and vias)*

Solid State Laser Spot-area Ablations



*Laser drilling
(i.e. through glass vias)*